

AMENDMENTS TO THE SPECIFICATION

Please accept the amended Abstract of the Disclosure as follows:

~~A wafer guide used in cleaning and/or drying processes of semiconductor wafers is provided.~~ The wafer guide includes a horizontal support panel and at least three vertical panels attached on one surface of the support panel. Each of the vertical panels has a vertical body panel and a plurality of protrusions upwardly extended from a top surface of the vertical body panel. Gap regions between the protrusions act as slots for holding wafers. Sidewalls of the slots have a convex shaped profile when viewed from a top view, and bottom surfaces of the slots also have a convex shaped profile when viewed from a cross sectional view that crosses the vertical panels. Accordingly, ~~contact areas between the wafers and the wafer guide are reduced to improve a drying efficiency of the wafers.~~